

FIG. 1

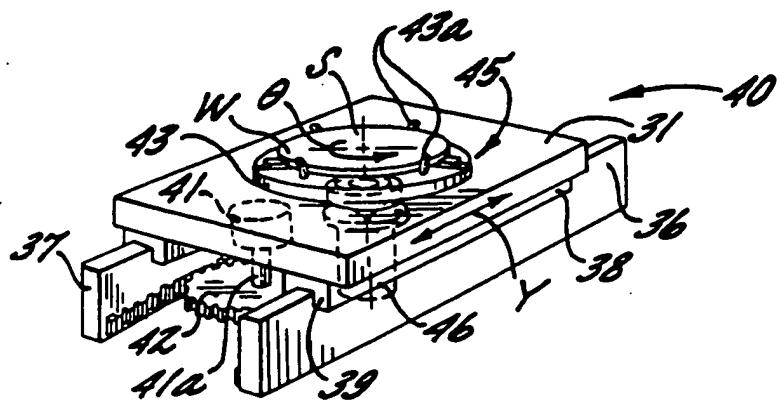


FIG. 2

Applicant(s): Michael E. Fossey et al.

**WAFER INSPECTION SYSTEM FOR DISTINGUISHING PITS
AND PARTICLES**

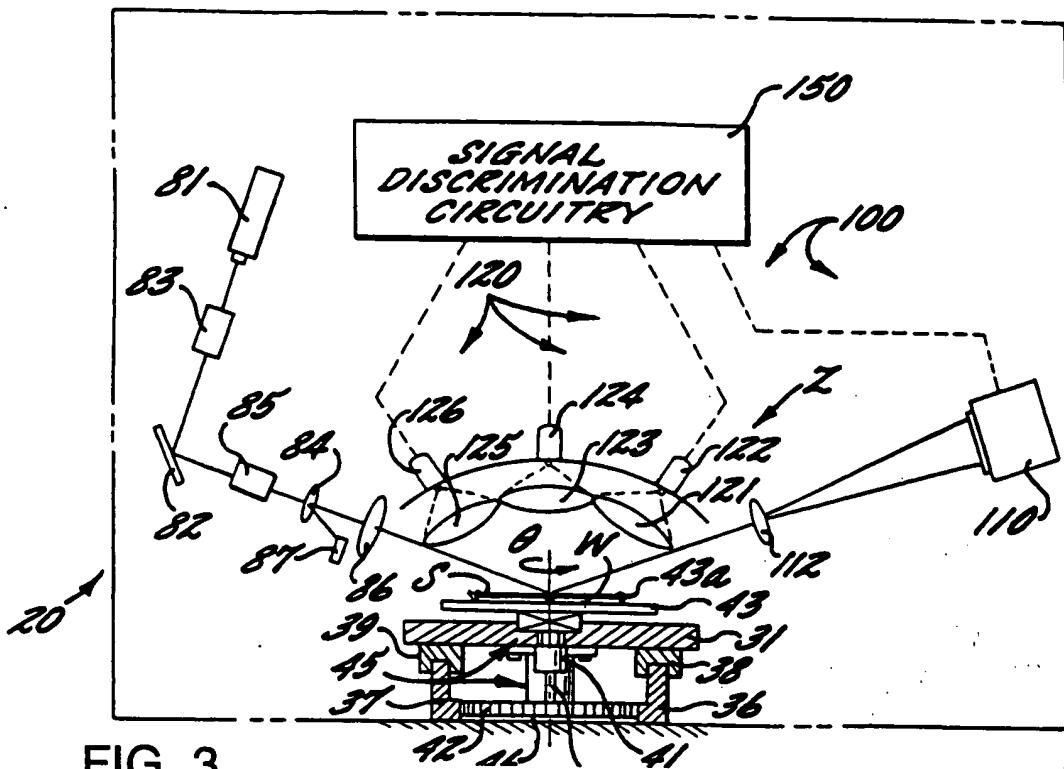


FIG. 3

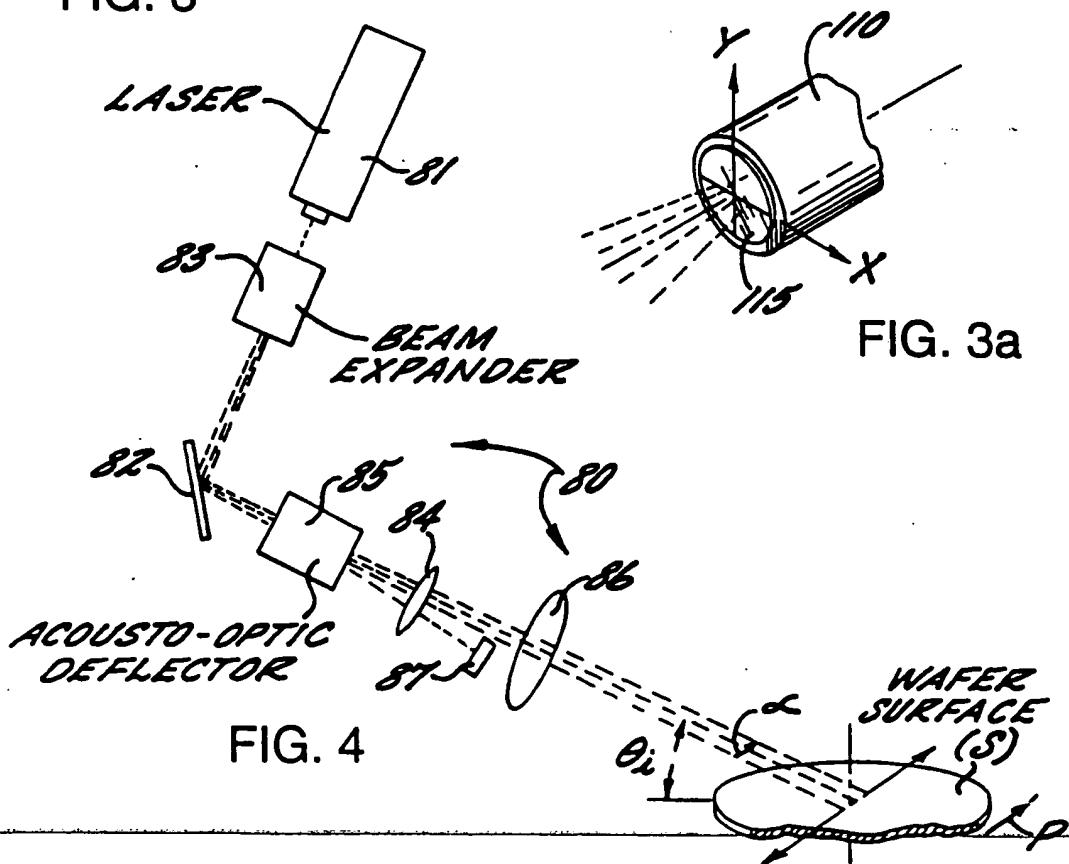


FIG. 4

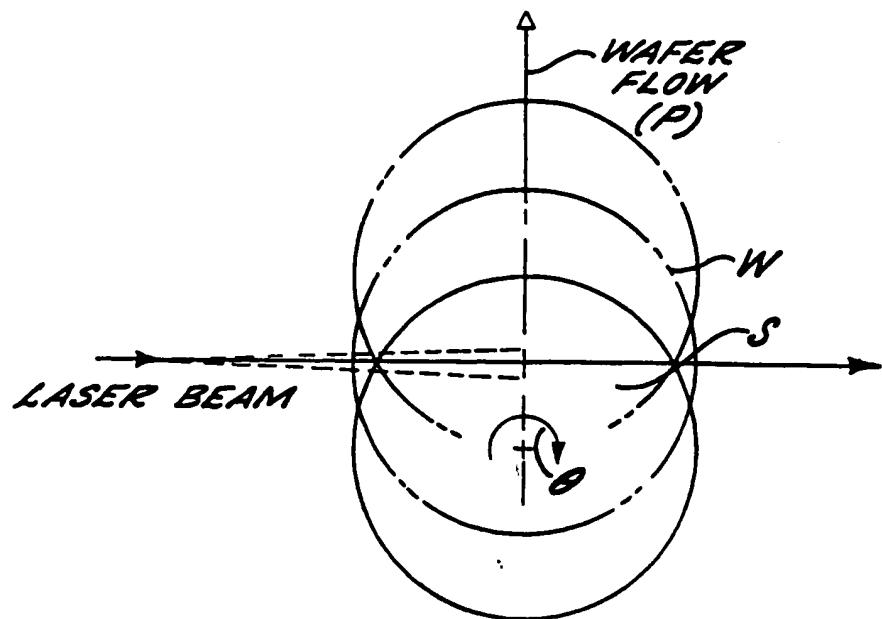


FIG. 5

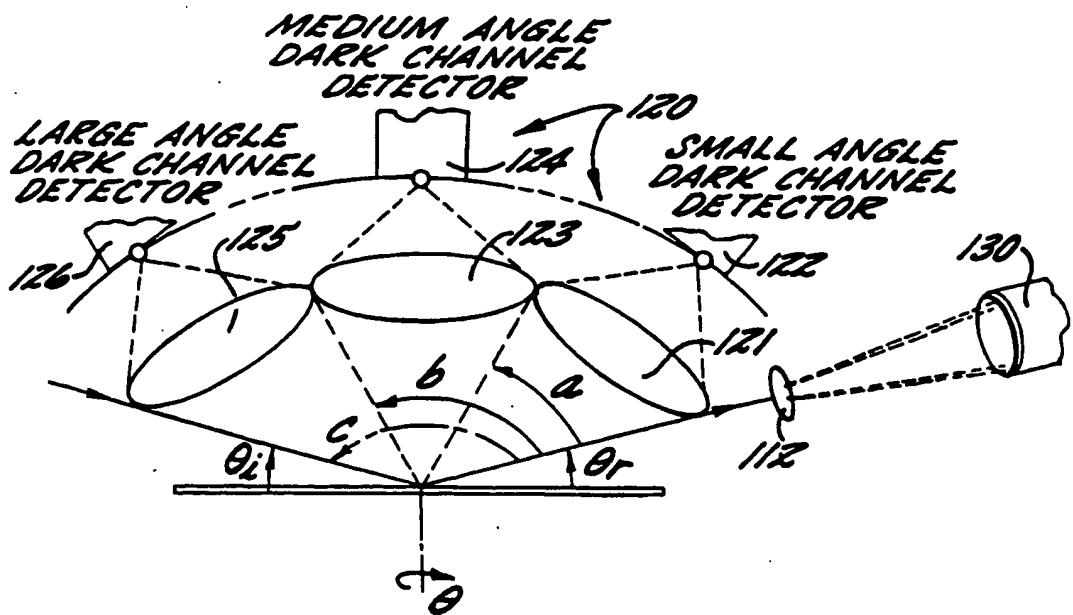


FIG. 6

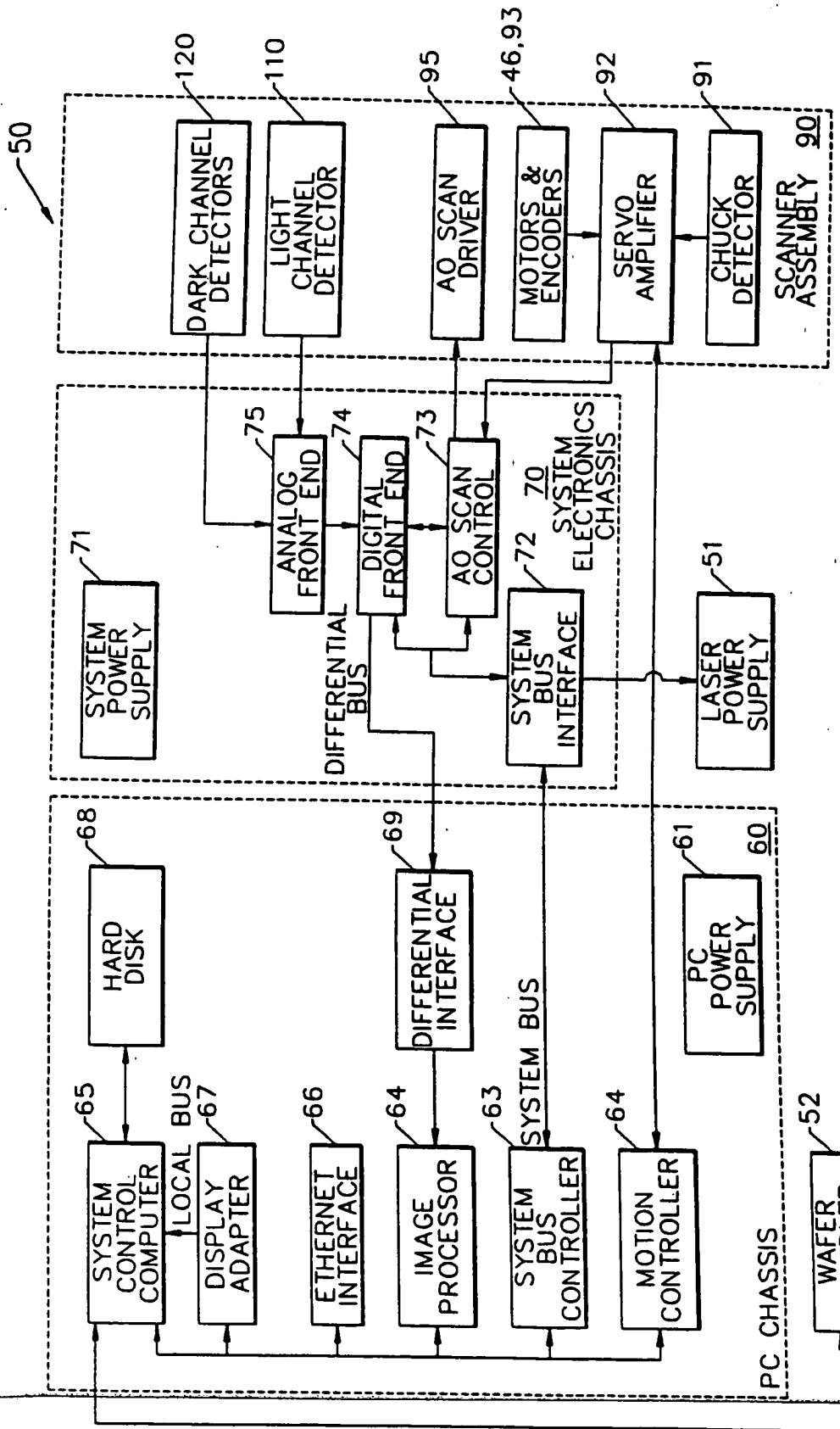


FIG. 7

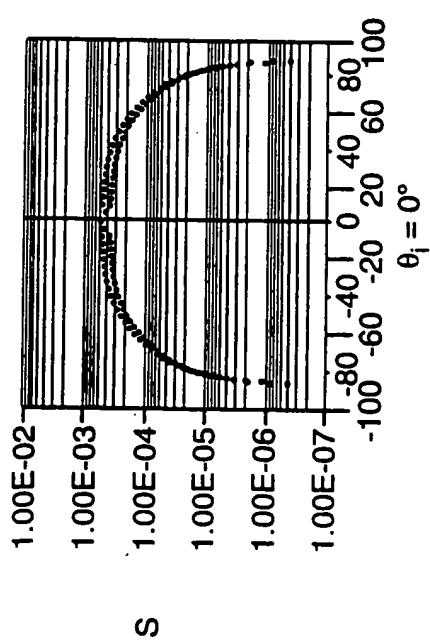


FIG. 8A

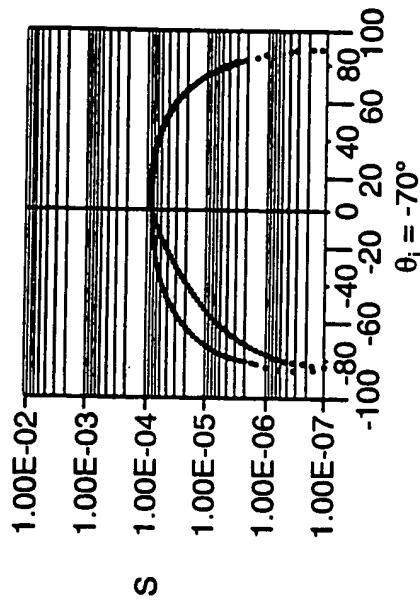


FIG. 8B

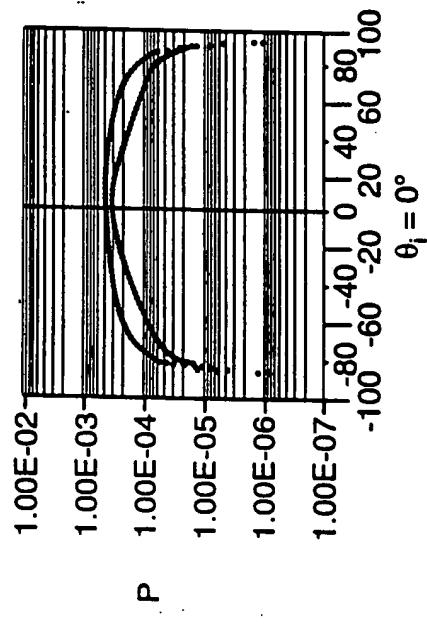


FIG. 8C

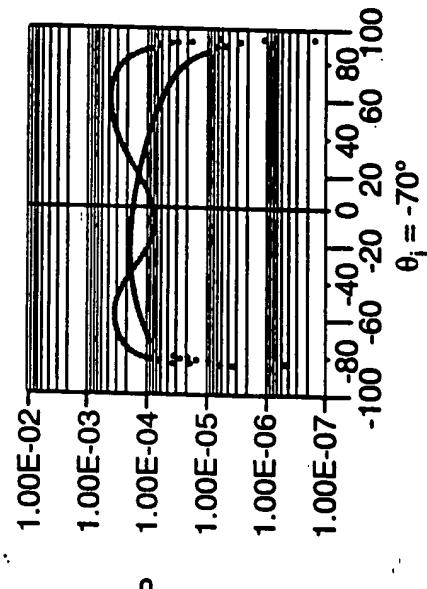


FIG. 8D

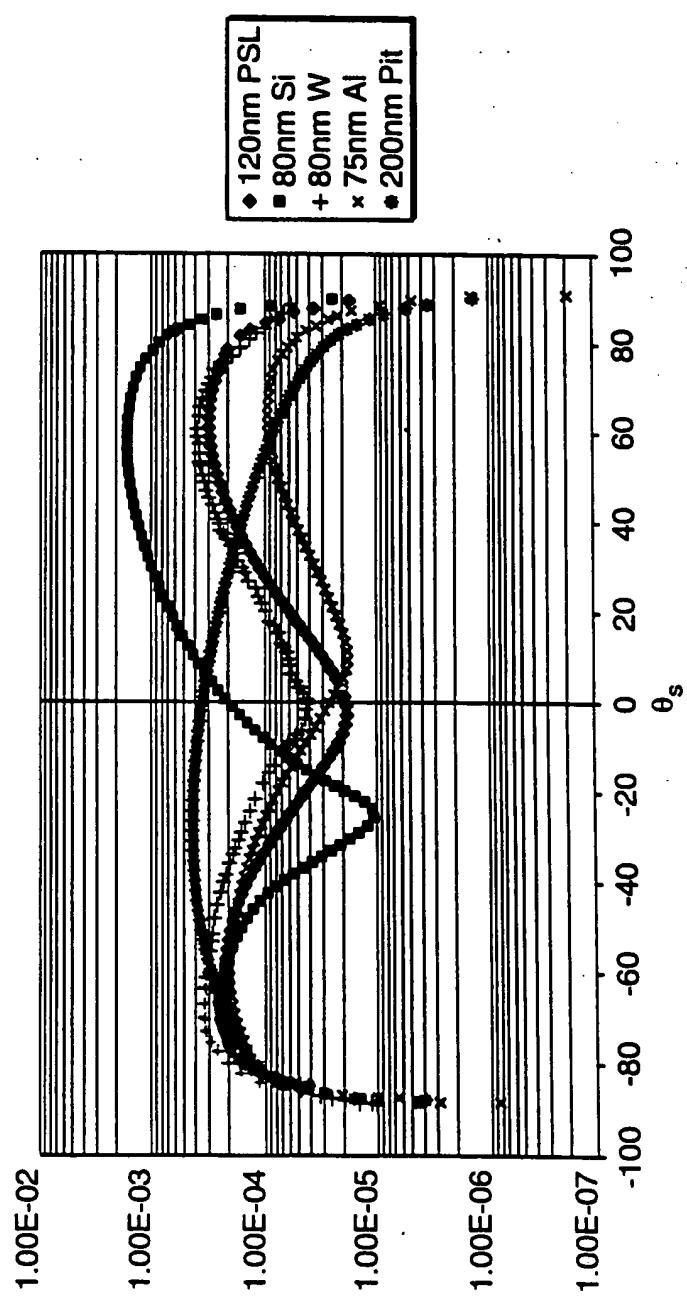


FIG. 9

EXPERIMENTAL RESULTS

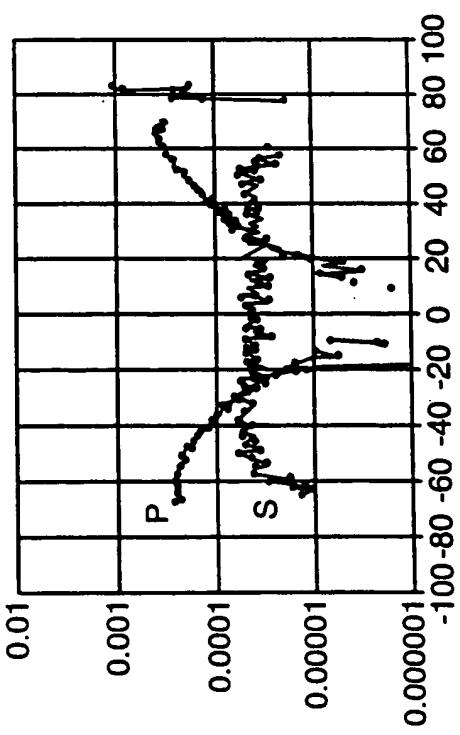


FIG. 10A

MODELED RESULTS

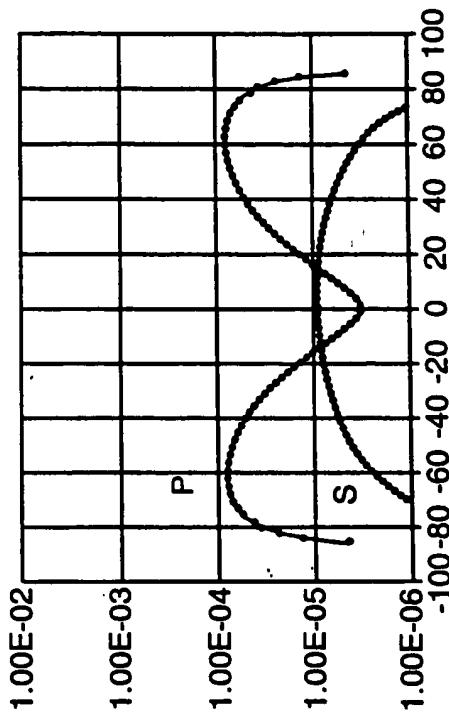


FIG. 10B

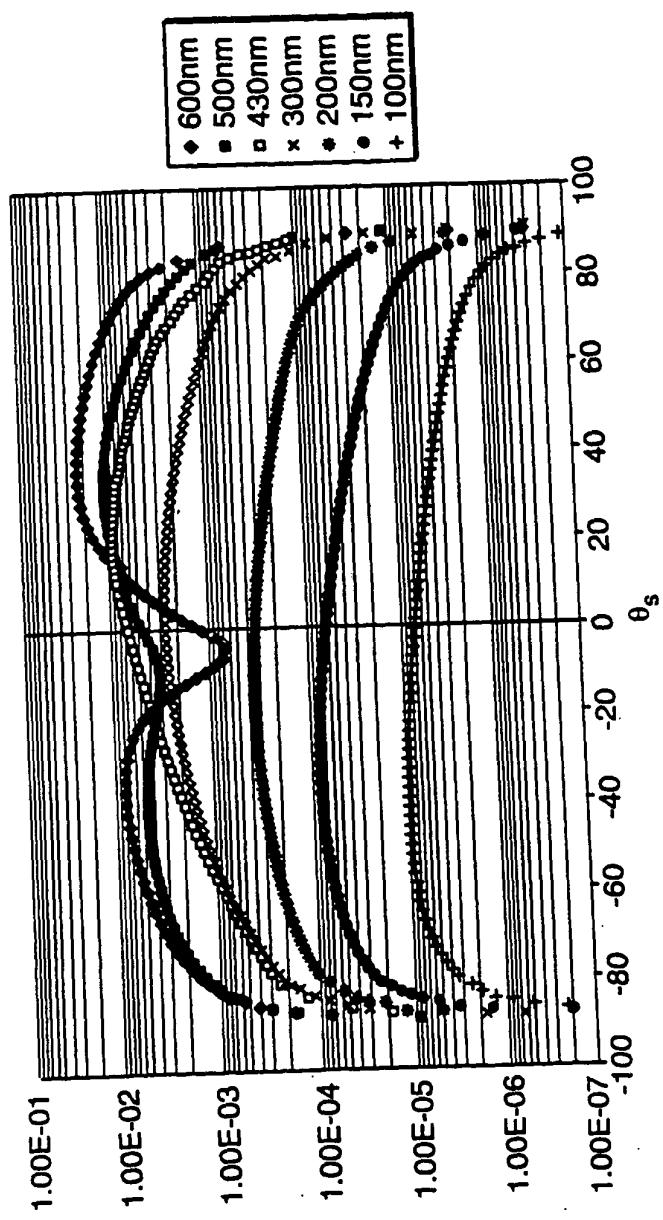


FIG. 11

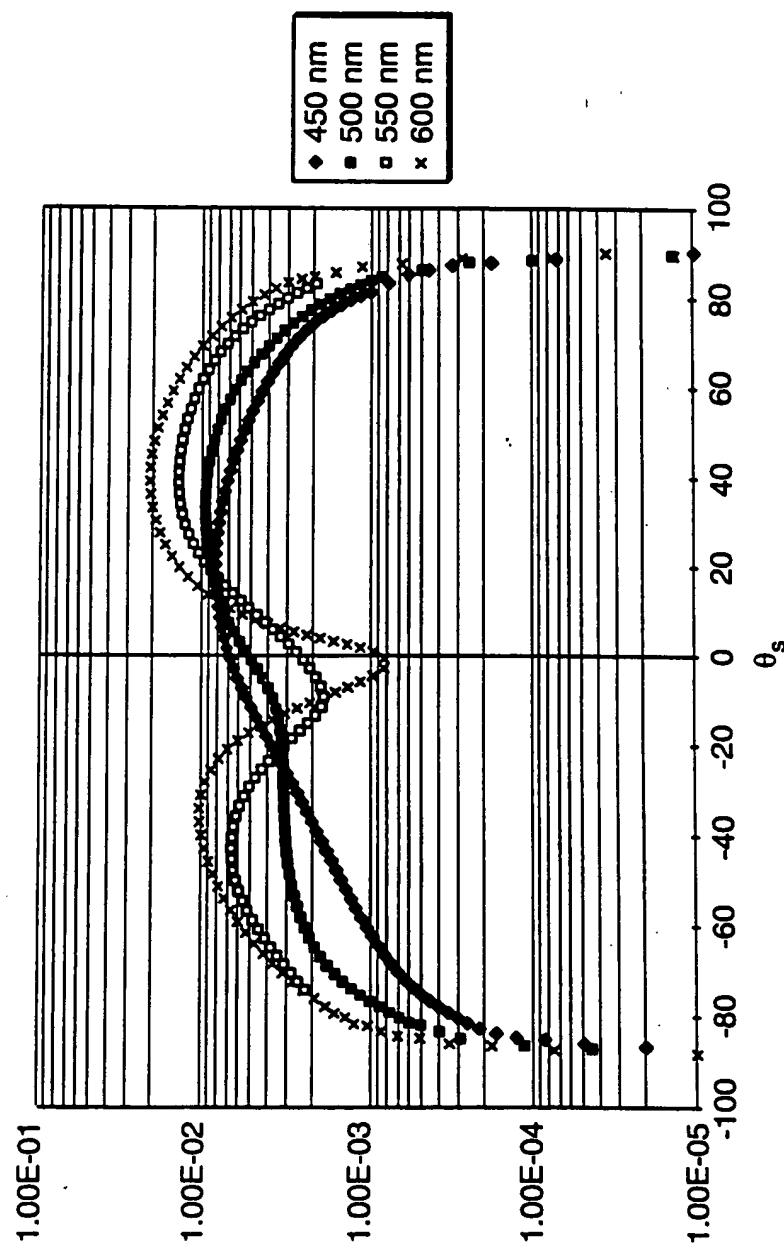


FIG. 12

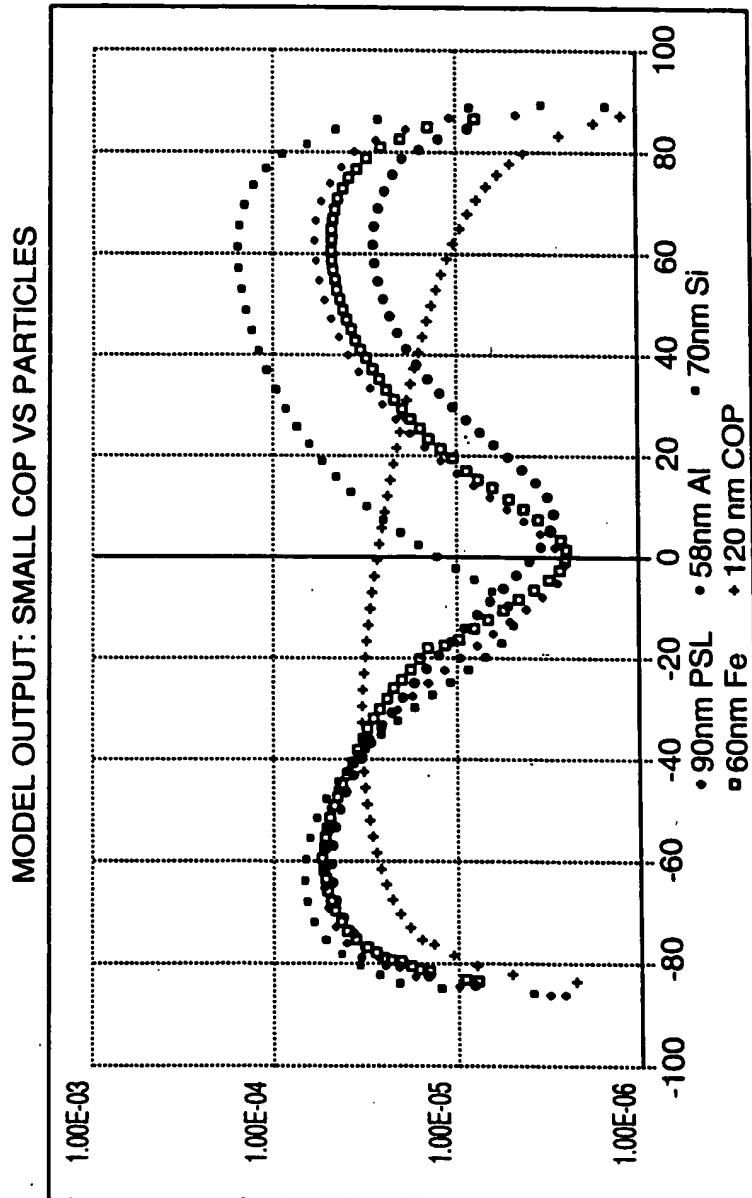


FIG. 13

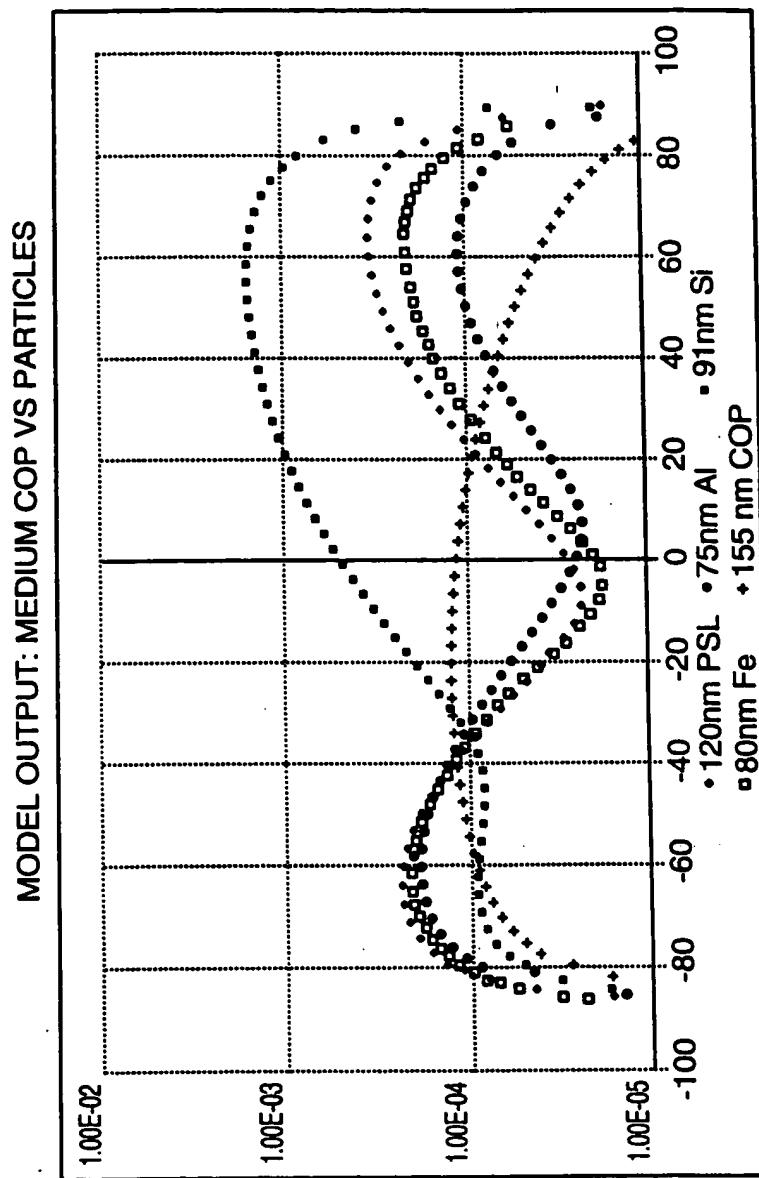


FIG. 14

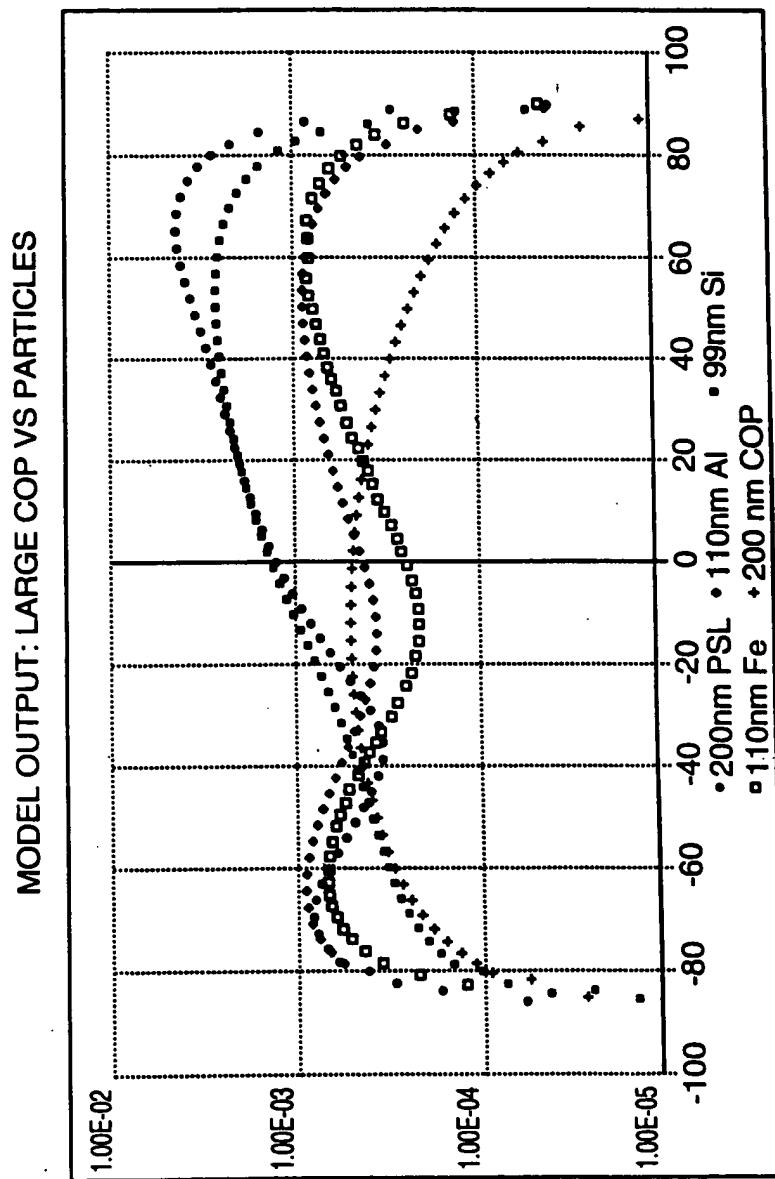


FIG. 15

COP ALGORITHM

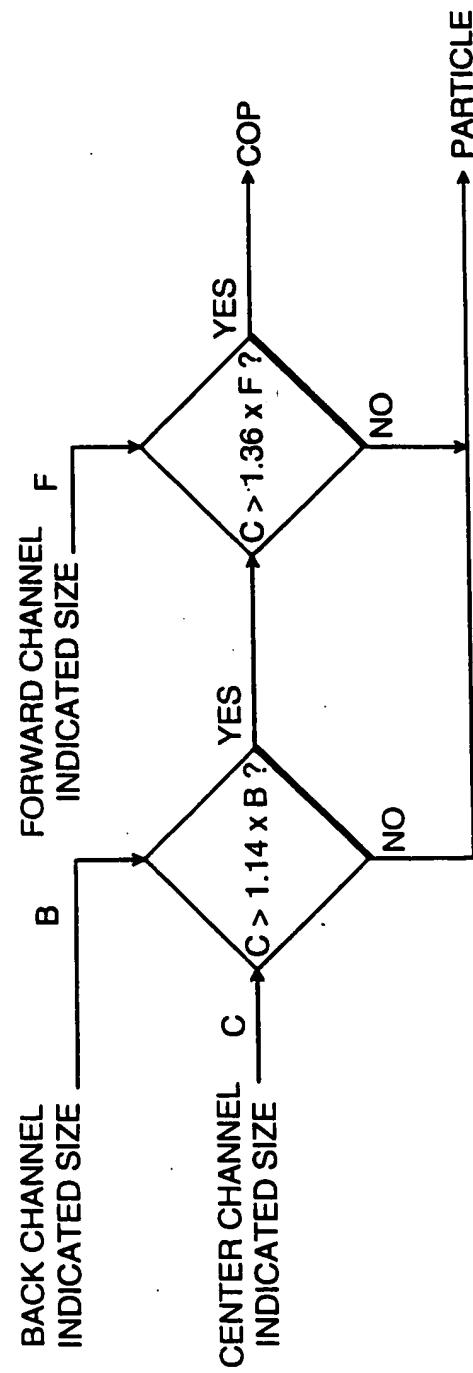


FIG. 16

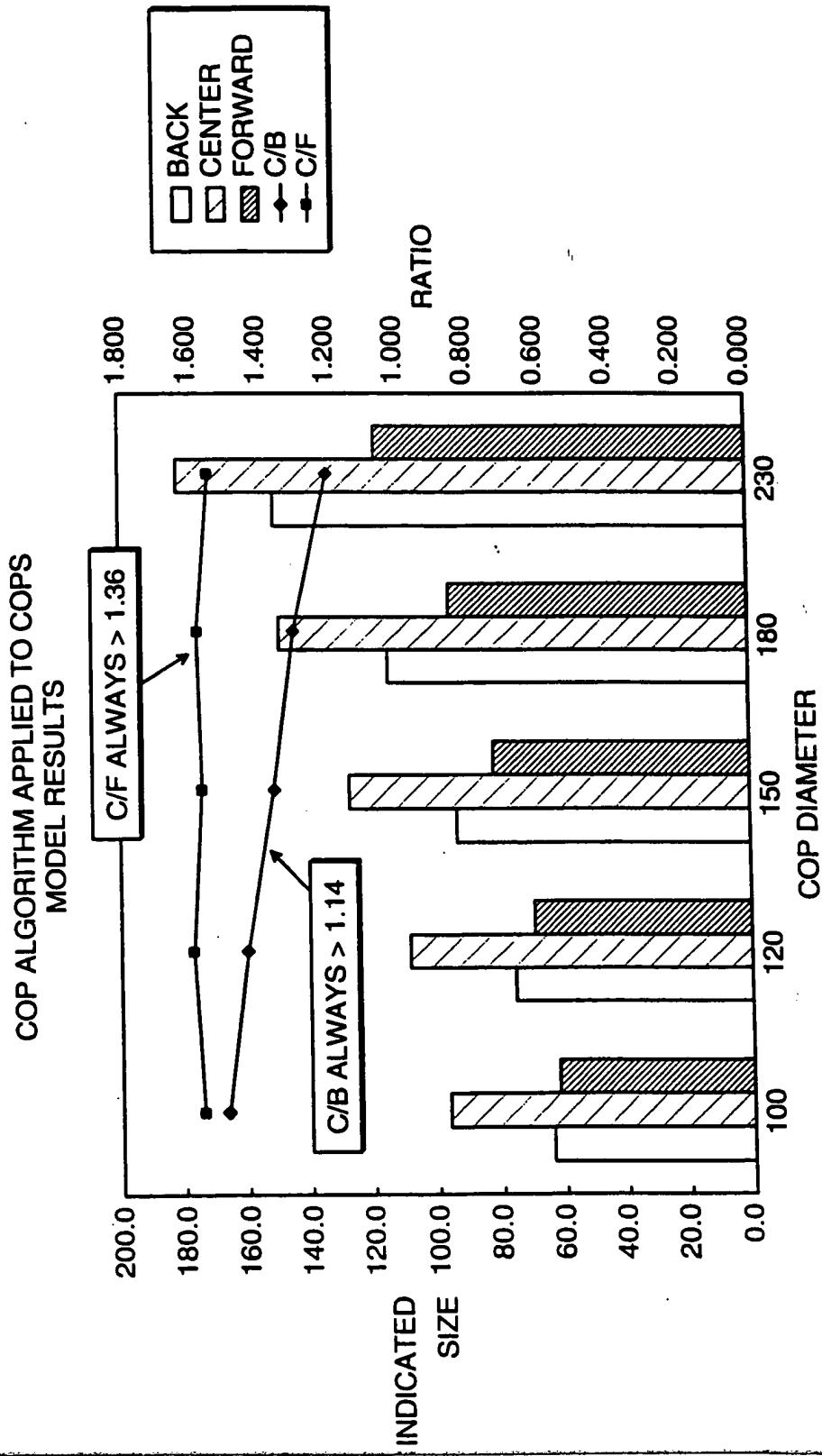


FIG. 17

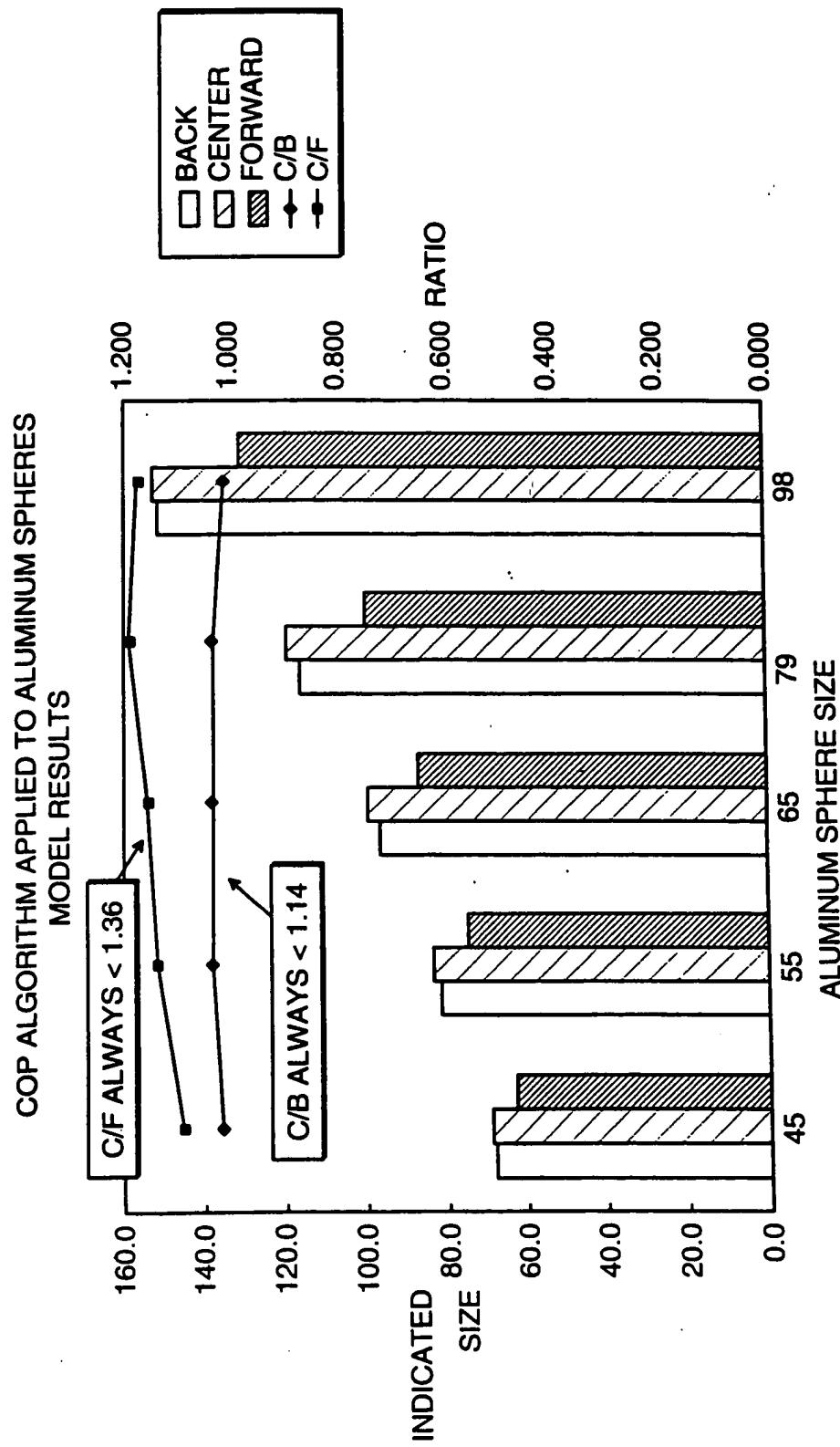


FIG. 18

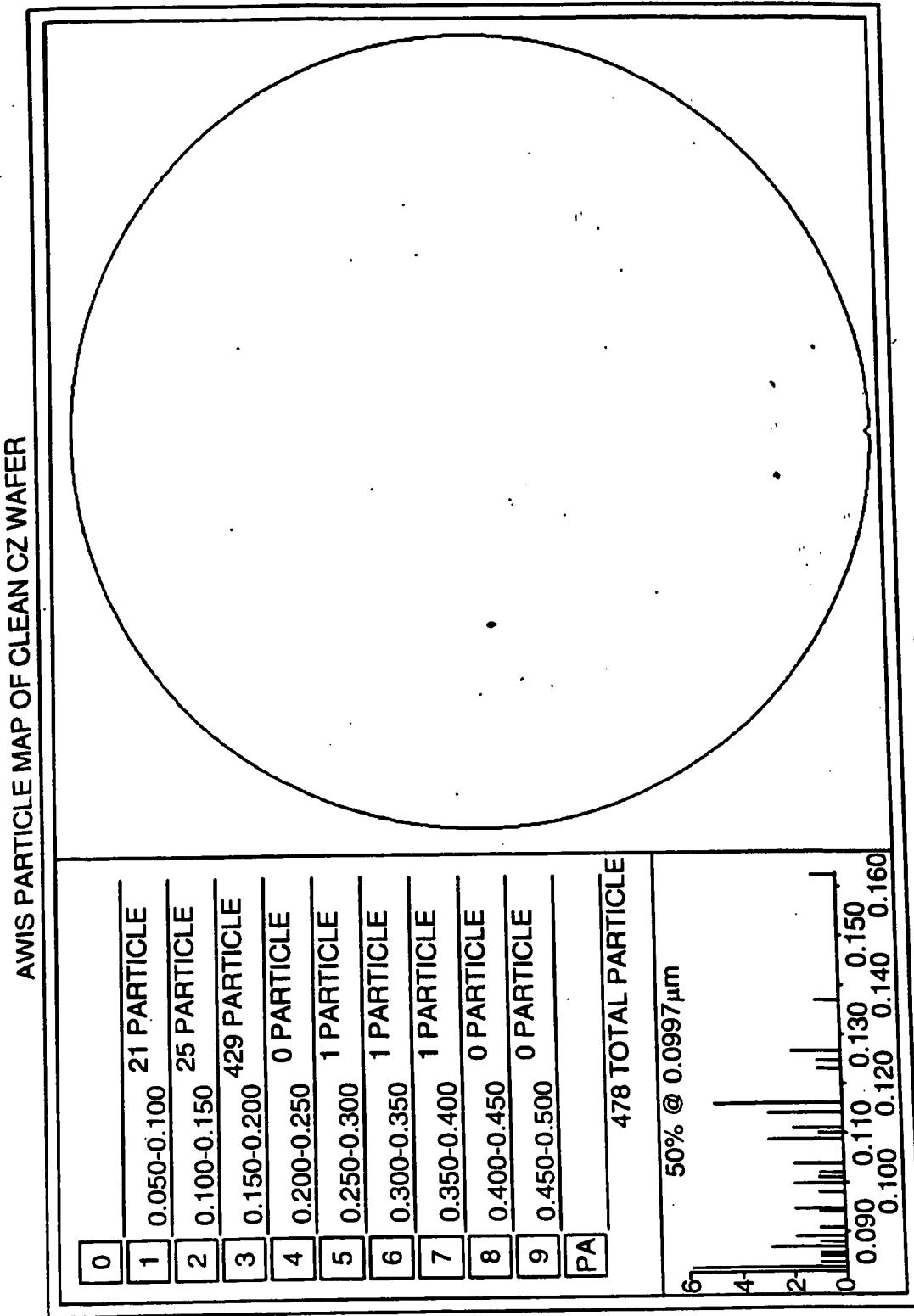


FIG. 19

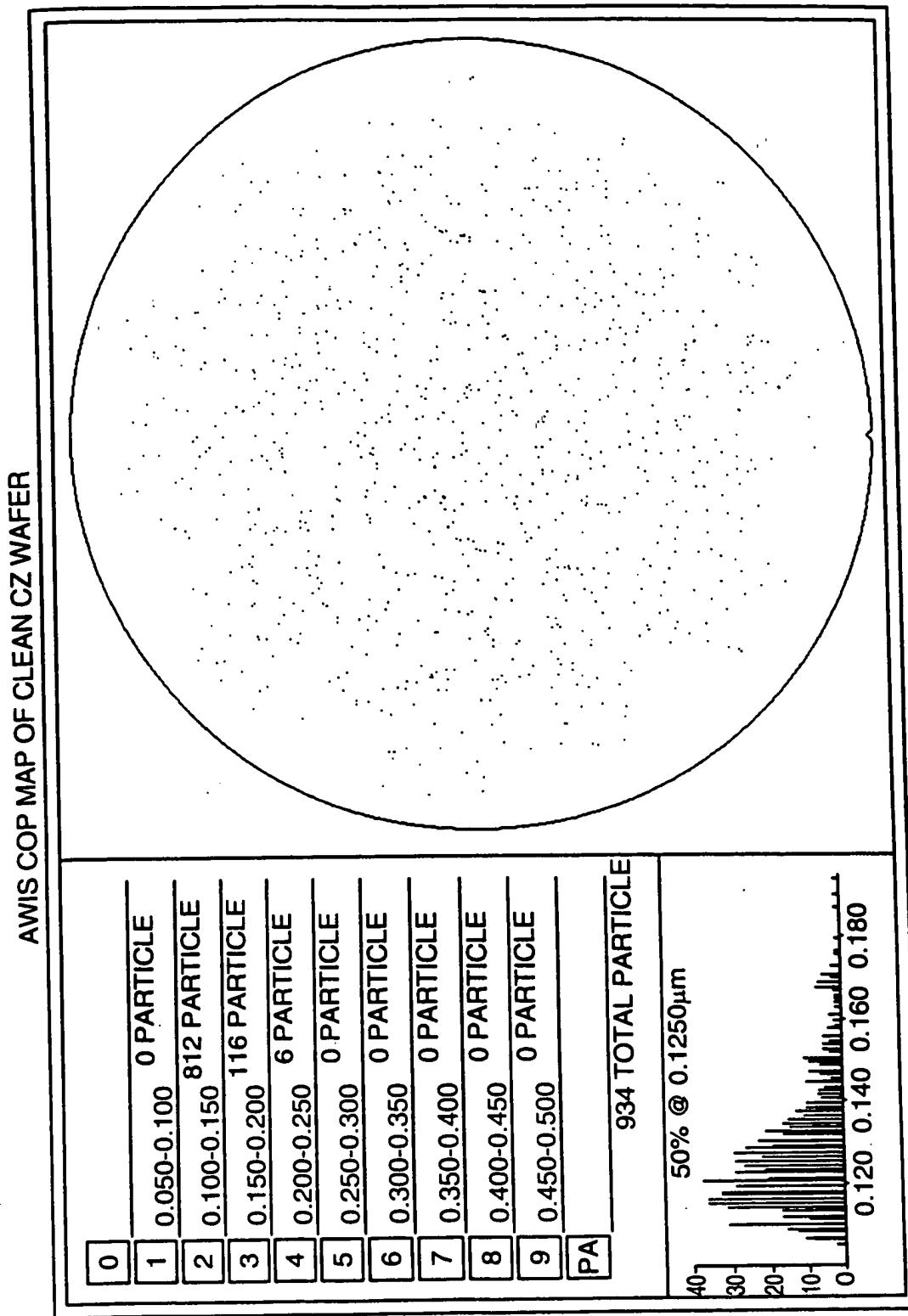


FIG. 20

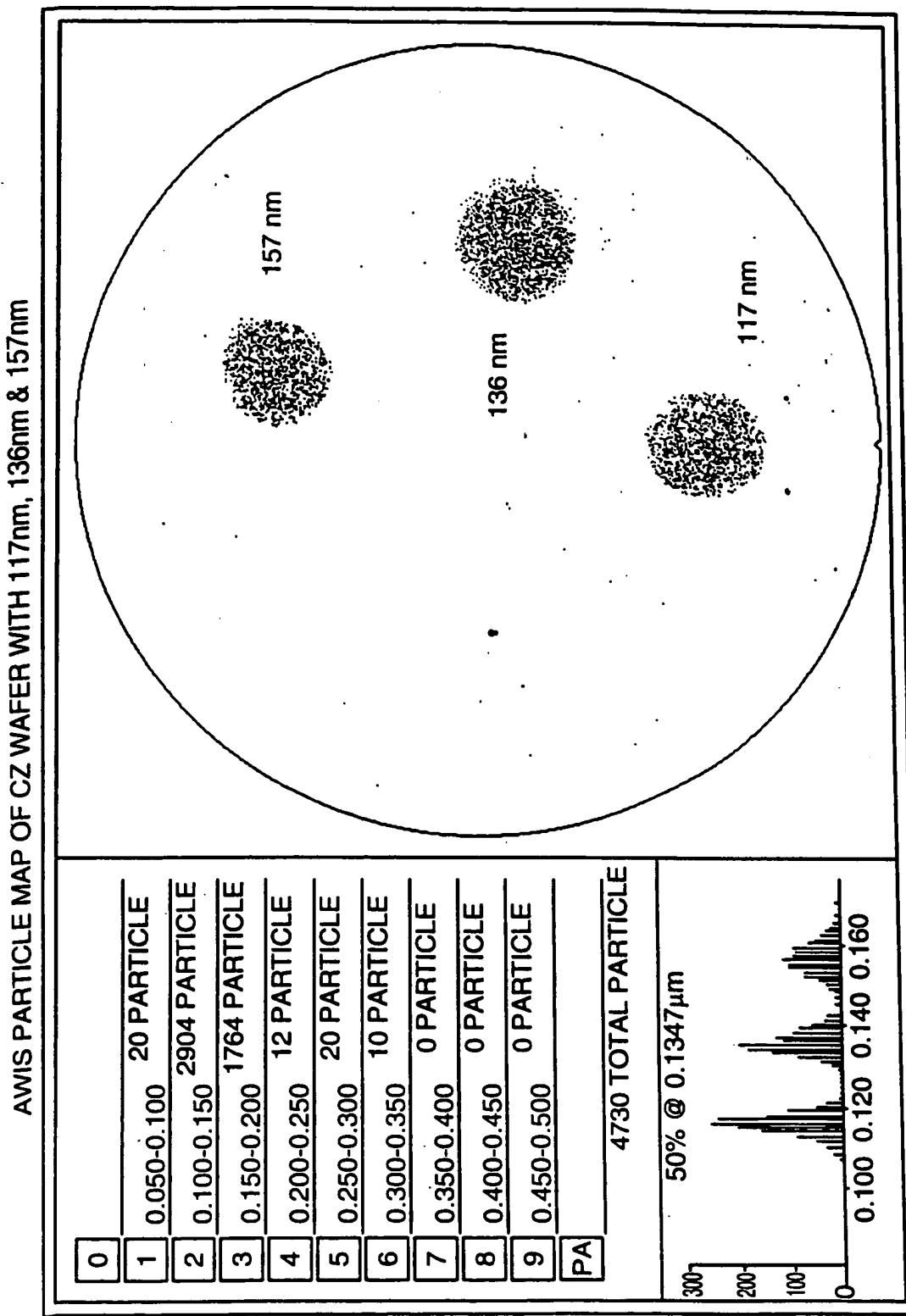


FIG. 21

AWIS COP MAP OF CZ WAFER WITH 117nm, 136nm & 157nm

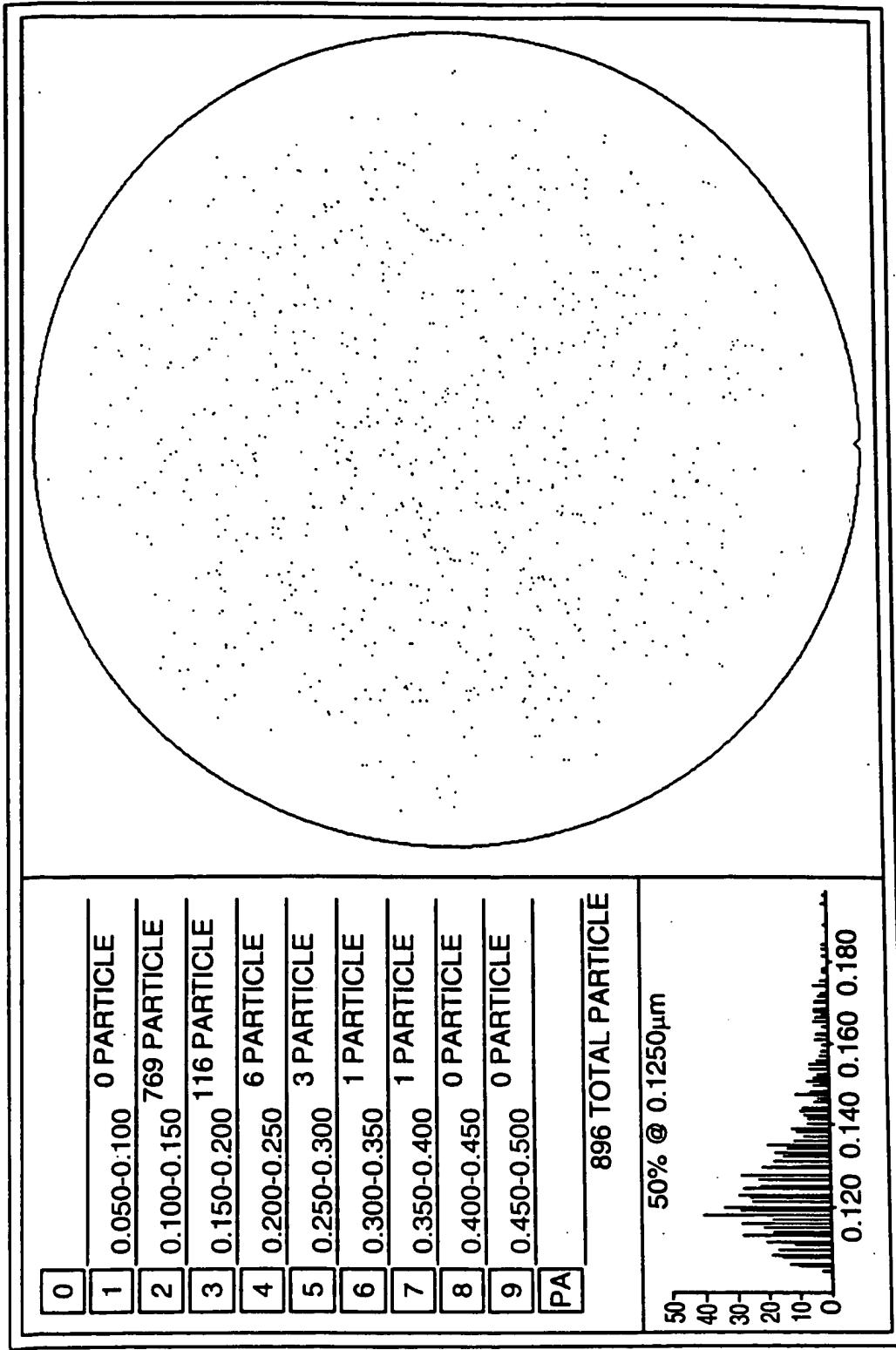


FIG. 22